

**REMARKS**

The final Office Action of June 30, 2006, has been received and reviewed.

Claims 1-37 and 65-103 are currently pending and under consideration in the above-referenced application. Of these, claims 65-68 stand rejected, while claims 1-37 and 69-103 have been allowed.

Reconsideration of the above-referenced application is respectfully requested.

**Rejections under 35 U.S.C. § 102**

Claims 65-68 stand rejected under 35 U.S.C. § 102(e) for reciting subject matter that is allegedly anticipated by that described in U.S. Patent Publication 2003/0080398 of Badehi (hereinafter "Badehi").

A claim is anticipated only if each and every element as set forth in the claim is found, either expressly or inherently described, in a single reference which qualifies as prior art under 35 U.S.C. § 102. *Verdegaal Brothers v. Union Oil Co. of California*, 2 USPQ2d 1051, 1053 (Fed. Cir. 1987). The identical invention must be shown in as complete detail as is contained in the claim. *Richardson v. Suzuki Motor Co.*, 9 USPQ2d 1913, 1920 (Fed. Cir. 1989).

Badehi discloses a process for fabricating and assembling packaged semiconductor devices that include contacts that extend along portions of the peripheral edges thereof. As depicted in FIG. 2C of Badehi, contacts 94 and 96 of two semiconductor devices 92 and 90, respectively, may be electrically connected to one another as one semiconductor device 92 is stacked upon the other semiconductor device 90, with contacts 94 and 96 in alignment.

Independent claim 65 is drawn to a method for assembling a chip-scale package with another semiconductor device component. The method of independent claim 65, as amended and presented herein, includes orienting a chip-scale package that includes contacts that extend along an entire height of an outer periphery thereof adjacent to another semiconductor device component and disposing intermediate conductive elements between at least some of the contacts and corresponding contacts of the semiconductor device component.

Badehi, in contrast, does not expressly or inherently describe a semiconductor device with at least some contacts including at least sections "that extend along an entire height of [an] outer

periphery” of the semiconductor device. Rather, the description of Badehi is limited to semiconductor devices with contacts that extend only partially across the peripheral edges thereof. *See, e.g.*, FIGs. 2A through 2C, which illustrated contacts 76, 86, 94, 96 that extend only half way across the outer peripheries of their respective semiconductor devices 70, 80, 92, 90.

As Badehi does not expressly or inherently describe, or anticipate, each and every element of independent claim 65, it is respectfully submitted that, under 35 U.S.C. § 102(e), the subject matter recited in independent claim 65 is allowable over the subject matter described in Badehi.

Claims 66 and 67 are both allowable, among other reasons, for depending directly from independent claim 65, which is allowable.

The chip-scale package fabrication method of independent claim 68 includes “disposing intermediate conductive elements between peripheral sections of . . . contacts of the chip-scale package and corresponding contacts . . . of [a] semiconductor device component.” The corresponding contacts of the semiconductor device component are “exposed beyond the outer periphery of the chip-scale package . . .”

It is evident from FIG. 2C of Badehi that such electrical connection is established at locations between the semiconductor devices 90 and 92, not with the *peripheral sections* of the contacts 96 or 94 of either semiconductor device 90 or 92. As such, Badehi does not anticipate each and every element of independent claim 68, as would be required to maintain the 35 U.S.C. § 102(e) rejection of independent claim 68.

It is respectfully requested that the 35 U.S.C. § 102(e) rejections of claims 65-68 be withdrawn and that each of these claims be allowed.

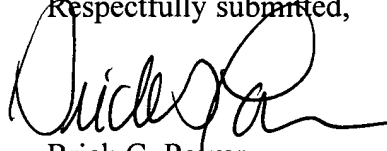
#### **Allowed Claims**

The allowance of claims 1-37 and 69-103 is gratefully acknowledged.

**CONCLUSION**

It is respectfully submitted that each of claims 1-37 and 65-103 is allowable. An early notice of the allowability of each of these claims is respectfully solicited, as is an indication that the above-referenced application has been passed for issuance. If any issues preventing allowance of the above-referenced application remain which might be resolved by way of a telephone conference, the Office is kindly invited to contact the undersigned attorney.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Brick G. Power", written over the typed name.

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